



NOTES:

MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
- 2.CONTACT MATERIAL :PHOSPHOR BRONZE Ø0.46mm.
- 3.PLATING :GOLD PLATING OVER NICKEL.
- 4.SHIELD :0.20mm THICKNESS COPPER ALLOY WITH NICKEL PLATED.

ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.
- 2.CURRENT RATING :1.5 AMP.
- 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.
- 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC .
- 5.DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN.

MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.
- 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

ENVIRONMENTAL:

- 1. STORAGE : -40°C~+85°C
- 2. OPERATION : -40°C TO 70°C.

PC Board Layout
Component Side Shown

<p>RoHS Compliant</p>		<p>HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.</p>	
<p>APPD. 核准 Betty</p>	<p>SCALE 比例 参考</p>	<p>TOLERANCE 容許公差 .0 ± 0.30 .00 ± 0.20 ANG. ± 3°</p>	<p>PART NAME 品名 STACKED PCB JACK ROUND PIN 8P8C 2X8P GANG TYPE SHIELDED GOLD FLASH PLATING BLACK COLOR THREE TABS ROHS</p>
<p>DWG. 製圖 Betty</p>	<p>UNIT 單位 MM</p>	<p>SIZE. 紙張尺寸 A 4</p>	<p>PART NO. C0061-88PYGB00R</p>
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